

IBIS Chair's Report



<https://www.ibis.org/>

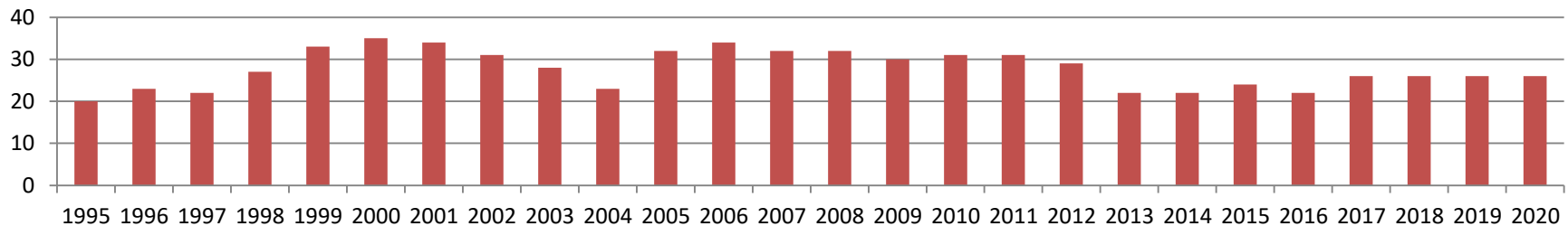
Randy Wolff
Micron Technology
Chair, IBIS Open Forum

DesignCon IBIS Summit
Santa Clara, CA
January 31, 2020

26 IBIS Members



Number of Members by Year



IBIS Officers 2019-2020

Chair: *Randy Wolff, Micron Technology*

Vice-Chair: *Lance Wang, Zuken USA*

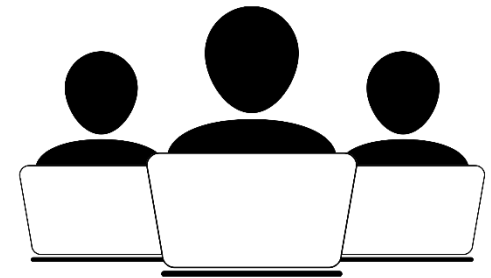
Secretary: *Curtis Clark, ANSYS*

Treasurer: *Bob Ross, Teraspeed Labs*

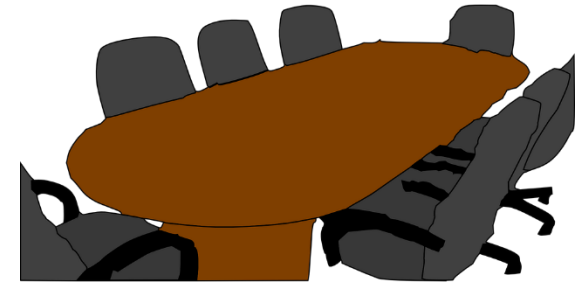
Librarian: *Anders Ekholm, Ericsson*

Postmaster: *Mike LaBonte, SiSoft (MathWorks)*

Webmaster: *Steve Parker, Marvell*



IBIS Meetings



- Weekly teleconferences
 - Quality Task Group (Tuesdays)
 - Advanced Technology Modeling Task Group (Tuesdays)
 - Interconnect Task Group (Wednesdays)
 - Editorial Task Group (some Fridays)
- IBIS Open Forum teleconference every 3 weeks
- IBIS Summit meetings: DesignCon, IEEE SPI, Shanghai, Taipei, Tokyo
- Participants: 368 in 2019

SAE ITC

- SAE Industry Technologies Consortia is the parent organization of the IBIS Open Forum
- IBIS is assisted by SAE employees José Godoy, Phyllis Gross, Laurie Strom
- SAE ITC provides financial, legal, and other services
- <http://www.sae-itc.org/>



Task Groups

- **Interconnect Task Group**
 - Chair: Michael Mirmak, Intel
 - http://ibis.org/interconn_wip/
 - Develop on-die/package/module/connector interconnect modeling BIRDs
- **Advanced Technology Modeling Task Group**
 - Chair: Arpad Muranyi, Mentor, A Siemens Business
 - http://ibis.org/atm_wip/
 - Develop most other technical BIRDs
- **Quality Task Group**
 - Chair: Mike LaBonte, SiSoft (MathWorks)
 - http://ibis.org/quality_wip/
 - Oversee IBISCHK parser testing and development
- **Editorial Task Group**
 - Chair: Michael Mirmak, Intel
 - http://ibis.org/editorial_wip/
 - Produce IBIS Specification documents

BIRD = Buffer Issue Resolution Document

IBIS China Regional Forum

- Users group originally formed in 2016
- Restart of group initiated based on interest expressed during 2019 Asia Summits
- Meetings to be conducted in Mandarin with minutes provided in English
- Group to focus on IBIS support in China
 - BIRD development, Summit presentations and support
- Coming soon

IBIS Milestones

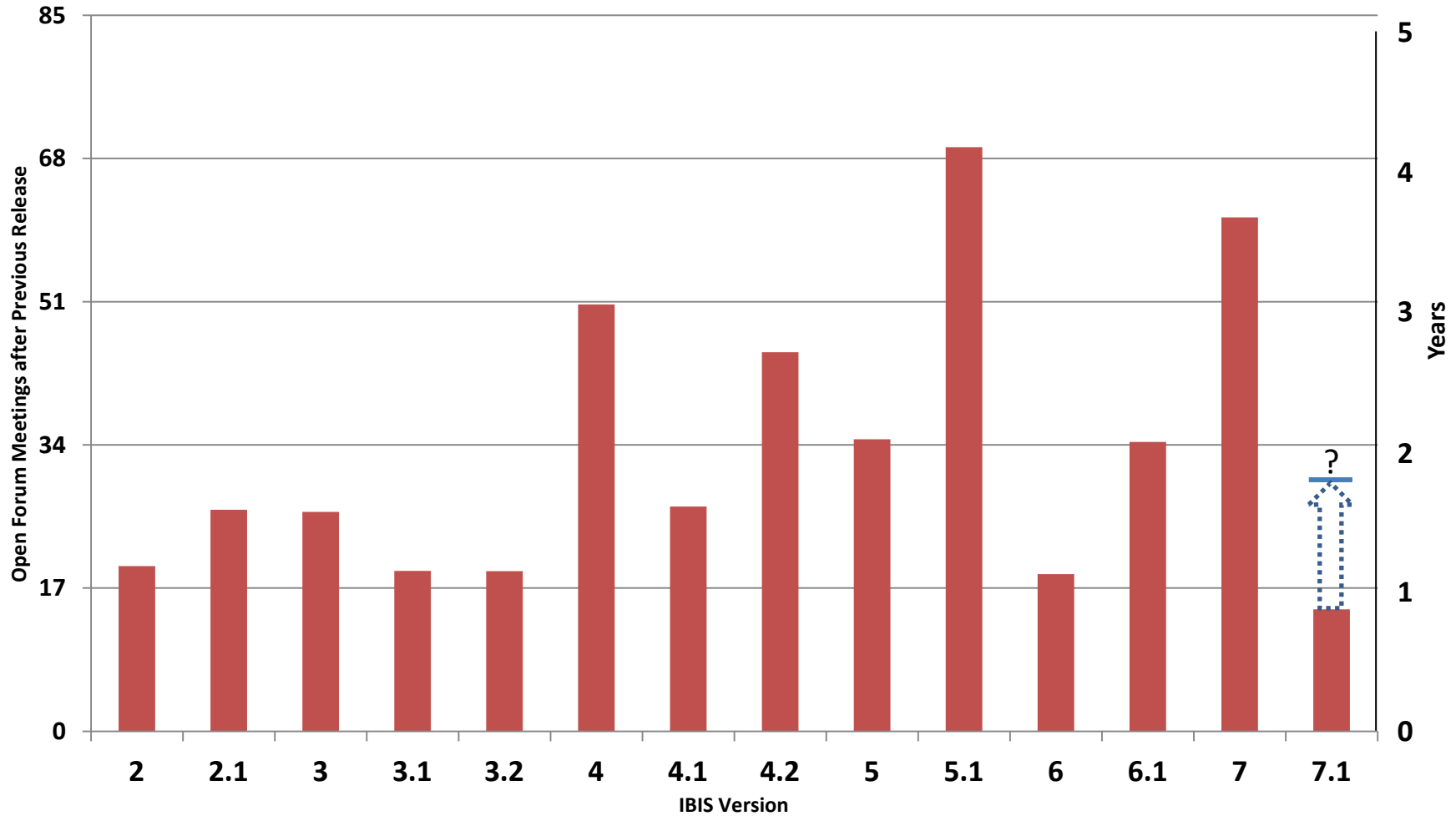
I/O Buffer Information Specification

- 1993-1994 **IBIS 1.0-2.1:**
 - Behavioral buffer model (fast simulation)
 - Component pin map (easy EDA import)
- 1997-1999 **IBIS 3.0-3.2:**
 - Package models
 - Electrical Board Description (EBD)
 - Dynamic buffers
- 2002-2006 **IBIS 4.0-4.2:**
 - Receiver models
 - AMS languages
- 2007-2012 **IBIS 5.0-5.1:**
 - IBIS-AMI SerDes models
 - Power aware
- 2013-2015 **IBIS 6.0-6.1:**
 - PAM4 multi-level signaling
 - Power delivery package models
- 2019 **IBIS 7.0:**
 - Back-channel support
 - Interconnect modeling using IBIS-ISS and Touchstone
- 2020? **IBIS 7.1**

Other Work

- 1995: **ANSI/EIA-656**
 - IBIS 2.1
- 1999: **ANSI/EIA-656-A**
 - IBIS 3.2
- 2001: **IEC 62014-1**
 - IBIS 3.2
- 2003: **ICM 1.0**
 - Interconnect Model Specification
- 2006: **ANSI/EIA-656-B**
 - IBIS 4.2
- 2009: **Touchstone 2.0**
- 2011: **IBIS-ISS 1.0**
 - Interconnect SPICE Subcircuit specification

IBIS Version Development



Planning for IBIS 7.1

BIRD	Title
181.1	I-V Table Clarifications
195.1	Enabling [Rgnd] and [Rpower] Keywords for Input Models
197.7	New AMI Reserved Parameter DC_Offset
198	Keyword additions for On Die PDN (Power Distribution Network) Modeling
199	Fix Rx_Receiver_Sensitivity Inconsistencies
200	C_comp Model Using IBIS-ISS or Touchstone
201	Back-channel Statistical Optimization
202	Electrical Descriptions of Modules

- Other BIRDs
 - 2 about redriver flow (BIRD166.4, BIRD190)
- Several BIRDs will take time for full reviews/updates before voting
- Plan to cut off new technical content later in 2020 to start editorial process

Green = currently accepted BIRD

[Thank You]



IBIS Open Forum:

Web: <https://www.ibis.org>

Email: ibis-info@freelists.org

We welcome participation by all IBIS model makers, EDA tool vendors, IBIS model users, and interested parties.